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| Form PTO-1449 U.S. Department of Commerce, Patent and Trademark Office | | | | Atty Docket No. | Serial No. |
| | | | | BDG018 | 10/646,415 |
| INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) | | | | Applicant | |
| | | | | Chia-Chung Wang et al. | |
| | | | | Filing Date | Group Art Unit |
| | | | | 8/22/03 | 2818 |

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| PHUONG T. DANG | 1/13/05 |

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| PD | AQ | U.S. Application Serial No. 09/465,024, filed December 16, 1999, entitled "Bumpless Flip Chip Assembly With Solder Via" |
| Examiner | Date Considered | PHUC T. DANG 1/13/05 |

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Foreign Patent Documents

| | | | | | | | Translation | |
|--|----|----------|------|---------|-------|----------|-------------|----|
| | | Document | Date | Country | Class | Subclass | Yes | No |
| | AN | | | | | | | |
| | AO | | | | | | | |

Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)

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| | AP | |
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| Examiner PHUC T. DANG | Date Considered 1/13/05 |
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your next communication to Applicant.

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|--|----|--|------|-------------------------------------|-------|----------------|----------------------------|
| Form PTO-1449 U.S. Department of Commerce, Patent and Trademark Office | | | | Atty Docket No. BDG018 | | Serial No. | |
| INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) | | | | Applicant Chia-Chung Wang et al. | | | |
| | | | | Filing Date | | Group Art Unit | |
| U.S. Patent Documents | | | | | | | |
| *Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate |
| | AA | | | | | | |
| Foreign Patent Documents | | | | | | | |
| | | Document | Date | Country | Class | Subclass | Translation |
| | AB | | | | | | Yes No |
| Other Art (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | |
| PD | AC | U.S. Application Serial No. 09/120,408, filed July 22, 1998, entitled "Flip Chip Assembly With Via Interconnection" | | | | | |
| | AD | U.S. Application Serial No. 09/643,212, filed August 22, 2000, entitled "Semiconductor Chip Assembly With Simultaneously Electroplated Contact Terminal and Connection Joint" | | | | | |
| | AE | U.S. Application Serial No. 09/643,214, filed August 22, 2000, entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint" | | | | | |
| | AF | U.S. Application Serial No. 09/643,213, filed August 22, 2000, entitled "Method Of Making A Support Circuit For A Semiconductor Chip Assembly" | | | | | |
| | AG | U.S. Application Serial No. 09/643,445, filed August 22, 2000, entitled "Method Of Making A Semiconductor Chip Assembly" | | | | | |
| | AH | U.S. Application Serial No. 09/665,928, filed September 20, 2000, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint" | | | | | |
| | AI | U.S. Application Serial No. 09/665,931, filed September 20, 2000, entitled "Method Of Making A Support Circuit With A Tapered Through-Hole For A Semiconductor Chip Assembly" | | | | | |
| PD | AJ | U.S. Application Serial No. 09/677,207, filed October 2, 2000, entitled "Method Of Making A Semiconductor Chip Assembly With A Conductive Trace Subtractively Formed Before And After Chip Attachment" | | | | | |
| Examiner PHUOC T. DANG | | Date Considered 4/13/05 | | | | | |
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|---|----|---|----------------------------|---------|-------------------------------------|----------|----------------------------|----|
| Form PTO-1449 U.S. Department of Commerce, Patent and Trademark Office | | | | | Atty Docket No. BDG018 | | Serial No. 10/646,415 | |
| INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) | | | | | Applicant Chia-Chung Wang et al. | | | |
| | | | | | Filing Date 8/22/03 | | Group Art Unit 2818 | |
| U.S. Patent Documents | | | | | | | | |
| *Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate | |
| | AA | | | | | | | |
| Foreign Patent Documents | | | | | | | | |
| | | | | | | | Translation | |
| | | Document | Date | Country | Class | Subclass | Yes | No |
| | | AB | | | | | | |
| Other Art (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | |
| PD | AC | U.S. Application Serial No. 09/865,367, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Simultaneously Electroplated Contact Terminal and Connection Joint" | | | | | | |
| PD | AD | U.S. Application Serial No. 09/864,555, filed May 24, 2001, entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint" | | | | | | |
| PD | AE | U.S. Application Serial No. 09/864,773, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint" | | | | | | |
| Examiner PHUC T. DANG | | | Date Considered 4/13/05 | | | | | |
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